# DATA SHEET FELIOS FLEX

Panasonic

Partner in North America Matrix

## FELIOS FLEX ADHESIVELESS FLEXIBLE LAMINATE

PCB Materials



#### Description

Panasonic FELIOS® Adhesiveless Flexible Laminates are the ideal choice for technically advanced Multilayer, Rigid-flex, Double and Single sided applications. FELIOS® Flex is an engineered, all Polyimide Substrate with premium copper foil bonded on two sides. FELIOS® Flex is currently used in many of today's advanced flexible applications such as Avionics, Computers, Medical Equipment, Hand Held Computers, and Instrumentation.

#### **Features**

- Superior Dimensional Stability
- Excellent Copper Foil Bond Strength
- Consistent dielectric thickness and electrical performance
- Halogen and Antimony Free
- UL94-V0, 160° C UL Operating Temperature
- Certified to IPC 4204/11, wide processing window
- 31032 Tested, 340° C Tg, RoHaS Compliant

## Product Offering

RF775-Double Sided	<u>Polyimide Thickness</u> .00058" .0008" .001" .002"	<u>Copper Foil RA*</u> Q, T, H, 1 oz Q, T, H, 1 oz Q, T, H, 1, 2 oz Q, T, H, 1, 2 oz
RF770-Single Sided	Polyimide Thickness .0008" .001" .002"	Copper Foil RA* T, H, 1 oz T, H, 1 oz T, H, 1 oz T, H, 1 oz



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**General Characteristics** 

Property  Unit  Test Method  κ-F775/779    25μ  50μ  100μ    Peel Strength  kN/m  IPC-TM-650 2.4.9
25µ  50µ  100µ    Peel Strength  kN/m  IPC-TM-650 2.4.9      1.7
As Fabricated  1.7  1.7  1.7    After Solder  1.7  1.7  1.7    Solder Float  288°C  Pass  Pass  Pass    Tensile Strength  MPA  IPC-TM-650 2.4.19  500  500  500    Tensile Modulus  Gpa  IPC-TM-650 2.4.19  7.1  7.1  7.1    Elongation  %  IPC-TM-650 2.4.19  93  93  93    Poisson's Ratio  0.3  0.3  0.3  0.3  0.3
After Solder  1.7  1.7  1.7  1.7    Solder Float  288°C  Pass  Pass
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Tensile Strength  MPA  IPC-TM-650 2.4.19  500  500  500    Tensile Modulus  Gpa  IPC-TM-650 2.4.19  7.1  7.1  7.1    Elongation  %  IPC-TM-650 2.4.19  93  93  93    Poisson's Ratio  0.3  0.3  0.3  0.3
Tensile Modulus  Gpa  IPC-TM-650 2.4.19  7.1  7.1  7.1    Elongation  %  IPC-TM-650 2.4.19  93  93  93    Poisson's Ratio  0.3  0.3  0.3  0.3
Elongation  %  IPC-TM-650 2.4.19  93  9
Poisson's Ratio 0.3 0.3 0.3
MIT Folding Endurance JIS C6471 R=0.38 220 60
Water Absorption % IPC-TM-650 2.6.2 1 1 1
Moisture Absorption % 23°C, 50%RH, 24 hr 0.7 0.7 0.7
Dielectric Thickness % IPC-TM-650 4.6.2 ±10 ±10 ±10
Tolerance
UL Flammability UL-94 94V-0 94V-0
Dielectric Constant 1 MHz IPC-TM-650 2.5.5.3 3.2 3.2 3.2
Dissipation Factor 1 MHz IPC-TM-650 2.5.5.3 0.002 0.002 0.002
Dielectric Strength kV/mil ASTM-D-149 7 7 7 7
Volume Resistivity ohm-cm IPC-TM-650 2.5.17.1 >1E+14 >1E+14 >1E+1
Surface Resistivity ohms JPC-TM-650 2.5.17.1 >1E+14 >1E+14 >1E+14
Moisture & Insulation ohms IPC-TN-650 2.63.2 >1E+13 >1E+13 >1E+13
Resistance
Initiation Tear Strength g 2.4.26 1700
Chemical Resistance min, % 2.3.2 Pass, >95 Pass, > 95 Pass, >
Propagation Tear Strength g 2.4.17.1 10 20
Solderability IPC-S-804,M.1 Pass Pass Pass
Glass Transition (Tg) C 343 343 343
Flexural Endurance min, cycles 2.4.3 >10000 >10000 >1000
Dimensional Change % IPC-TM-650 2.2.4 (B) 0.017/0.030 0.009/0.016 0.010/0.
after etch MD/TD
Dimensional Change % IPC-TM-650 2.2.4 0.012/0.009 0.007/0.010 0.007/0.
after heat MD/TD
Coefficient of ppm/k TMA 259°C-100°C 18 18 18
Thermal Expansion 5°C/min, 500g
Coefficient of ppm/%RH 23°C, 24 hrs 10 10 10
Humidity Expansion
Thermal Conductivity W/mK Laser Flash Method 0.24 0.24 0.24
Specific Heat J/gK Laser Flash Method 1.13 1.13 1.13
Densky g/cm3 Laser Flash Nethod 1.47 1.47 1.47

## Contact Us

For more information about the Panasonic FELIOS® Adhesiveless Flexible Laminates, please contact our Customer, or Technical Service Group at 866-862-8749, or visit our Website <u>www.matrixusa.us</u>

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